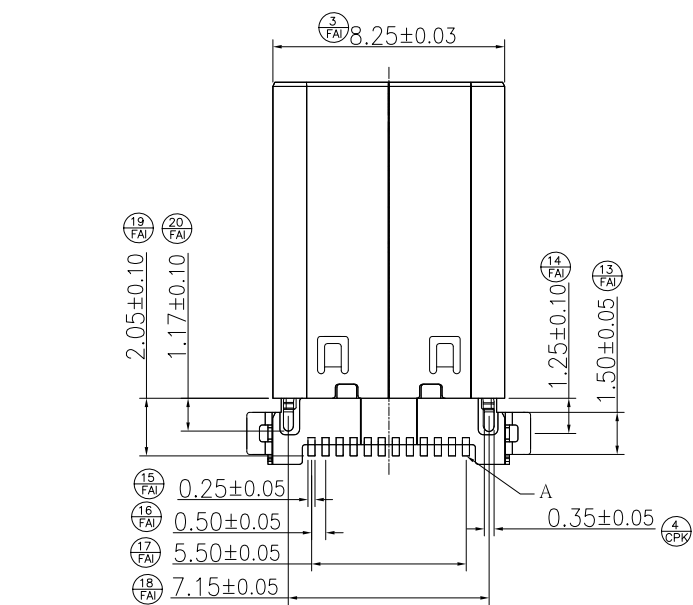
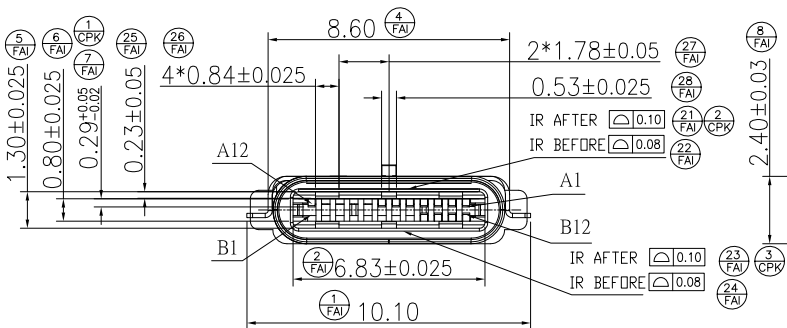
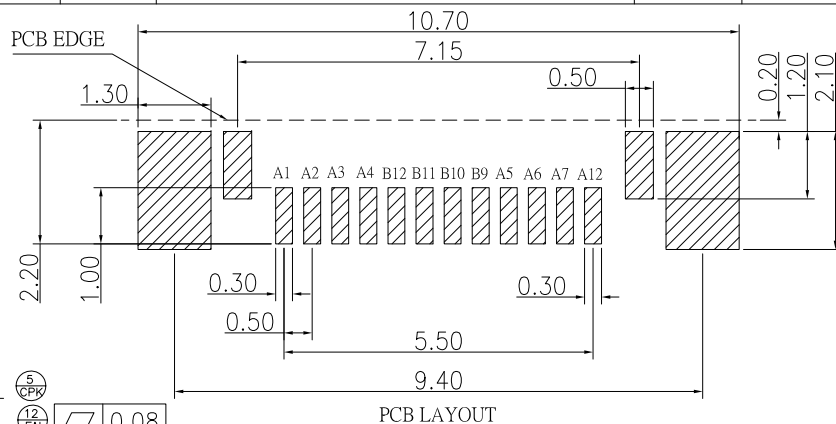
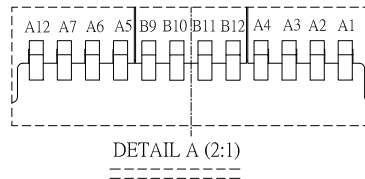
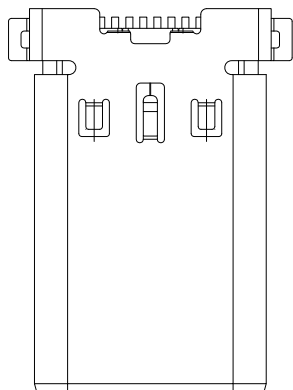


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/06/01	Phebe Su
A1			Change shell type	2015/06/18	Phebe Su
A2			Change shell type	2015/07/08	Phebe Su
A3			Change housing type	2015/08/03	Phebe Su
A4			Change shell type	2015/10/19	Phebe Su
A5			Change shell type	2016/10/19	Phebe Su
A6			Change shell type	2018/03/11	Phebe Su



NOTES:
1.MATERIAL:SEE NOTES 1
2.FINISH:

- 2.1 CONTACT: G/F PLATING ON CONTACT AREA, MATTE TIN PLATING ON SOLDER TAIL AREA, NICKEL UNDER PLATING.
- 2.2 SHELL: SOLDERABILITY NICKEL PLATING OVER ALL.

SPEC: Insertion force within the range from 5 n to 20 n.

Extraction force within the range of 8 n to 20 n. from 1 to 1,000 cycles and within the range of 6 n to 20 n. from 1,000 to 10,000 cycles.

MATRIX PART NO:

MATRIX USB MUSB 12 - 01 - 113 Series number
Pin Number Plating
01:Gold Flash
15:15u"
30:30u"

Pin Assignments:

A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1
GND					D-	D-	CC	VBUS	TX1	TX1	GND
								VBUS	RX1	RX1	GND
B1	B2	B3	B4	B5	B6	B7	B8	B9	B10	B11	B12

NOTES 1

NO	VARIETY	QTY	MATERIAL	REMARK
⑦	MYLAR	2	STAINLESS	
⑥	EMI PLATE	1	STAINLESS	
⑤	FRONT SHELL	1	STAINLESS	
④	LATCH	2	STAINLESS	
③	CONTACT	12	COPPER ALLOY	
②	SPACER	1	THERMAL PLASTIC	
①	HOUSING	1	THERMAL PLASTIC	
ITFM	DESCRIPTION	O'TY	MATERIAL	

Matrix Electronics Co.,Ltd

TOLERANCE:
X.X ±0.25
X.XX ±0.20
X.XXX ±0.10
ANGLE: ±3°

DESIGN BY : Phebe Su
DATE : 2018/03/11
CHECKED BY: Vicky Hsieh
DATE : 2018/03/11
APPROVED BY1: Richard Hsieh
DATE : 2018/03/11
APPROVED BY2: Richard Hsieh
DATE : 2018/03/11

PART NAME: USB 2.0 Type C PLUG
R/A_Offset Type_CL 0.25
PART NO. MUSB12-01-113
MOLD NO. NA
DRAW NO.
SHEET NO. 1 OF 1

UNIT: mm [inch]
SCALE:1:1 SIZE:A4